

Surface Mount Schottky Rectifier

Features

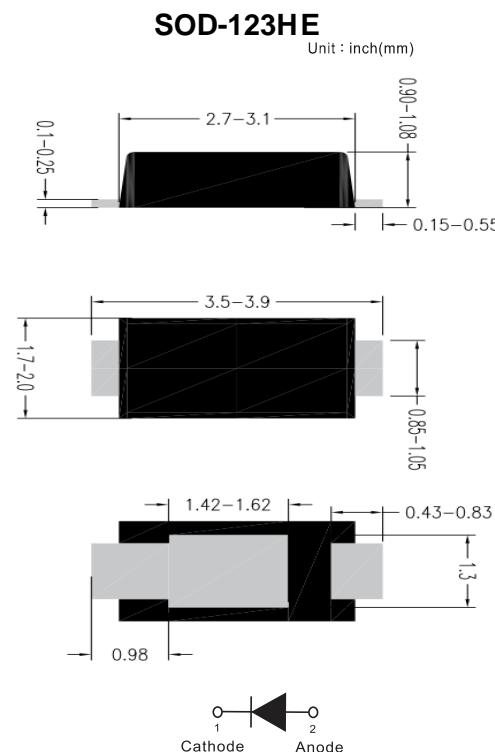
- Low profile package
- Ideal for automated placement
- Guardring for overvoltage protection
- Low power losses, high efficiency
- High forward surge capability
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- AEC-Q101 qualified (Automotive grade with suffix "Q".)
- Exsemi technology

Typical Applications

For use in low voltage high frequency inverters, freewheeling, DC/DC converters, and polarity protection applications.

Mechanical Data

- **Package:** SOD-123HE
Molding compound meets UL 94 V-0 flammability rating, RoHS-compliant, halogen-free
- **Terminals:** Tin plated leads, solderable per J-STD-002 and JESD22-B102
- **Polarity:** Cathode line denotes the cathode end



■Maximum Ratings (Ta=25°C Unless otherwise specified)

PARAMETER	SYMBOL	UNIT	SSD32 HE	SSD33 HE	SSD34 HE	SSD35 HE	SSD36 HE	SSD38 HE	SSD310 HE	SSD315 HE	SSD320 HE
Repetitive peak reverse voltage	VRRM	V	20	30	40	50	60	80	100	150	200
Average rectified output current @60Hz sine wave, Resistance load, Ta (FIG.1)	Io	A						3.0			
Surge(non-repetitive)forward current @60Hz half-sine wave, 1 cycle, Tj=25°C	IFSM	A						80			
Storage temperature	Tstg	°C				-55 ~+150			-55 ~+175		
Junction temperature	Tj	°C				-55 ~+150			-55 ~+175		
Typical Junction Capacitance measured at 1MHz and Applied on 4.0V.D.C	Cj	pF					165				

■Electrical Characteristics (Ta=25°C Unless otherwise specified)

PARAMETER	SYMBOL	UNIT	TEST CONDITIONS	SSD32 HE	SSD33 HE	SSD34 HE	SSD35 HE	SSD36 HE	SSD38 HE	SSD310 HE	SSD315 HE	SSD320 HE
Maximum instantaneous forward voltage drop per diode	VF	V	IFM=3.0A	0.55			0.70			0.80		
Maximum DC reverse current at rated DC blocking voltage per diode @ VRM=VRRM	IRRM	uA	Ta=25°C	5			1			100		
			Ta=100°C	200								

■ Thermal Characteristics ($T_a=25^\circ\text{C}$ Unless otherwise specified)

PARAMETER	SYMBOL	UNIT	SSD32 HE	SSD33 HE	SSD34 HE	SSD35 HE	SSD36 HE	SSD38 HE	SSD310 HE	SSD315 HE	SSD320 HE
Thermal Resistance	R _{θJ-A}	°C/W									70 ¹⁾
	R _{θJ-L}										16 ¹⁾

Note:

(1) Thermal resistance between junction and ambient and between junction and lead mounted on P.C.B with 3mm*3mm copper pad areas.

■ Characteristics (Typical)

FIG1:Io-TL Curve

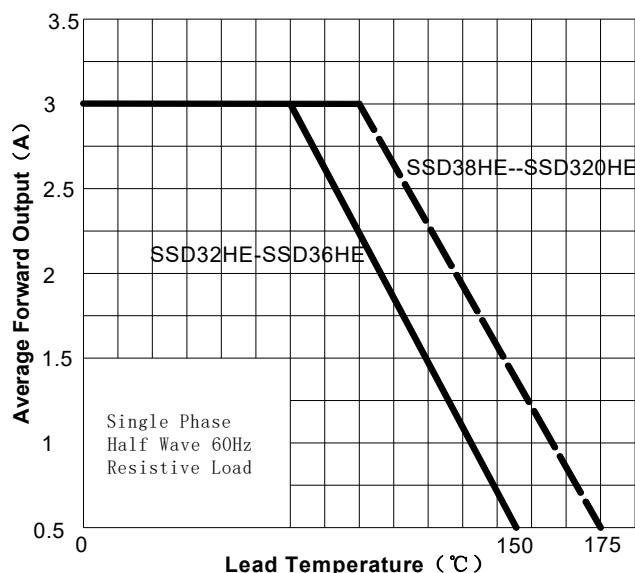


FIG2: Surge Forward Current Capability

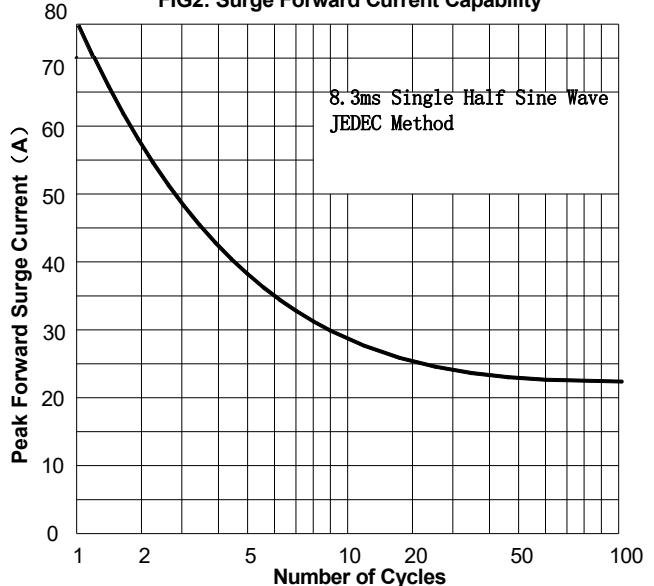


FIG3: Forward Voltage

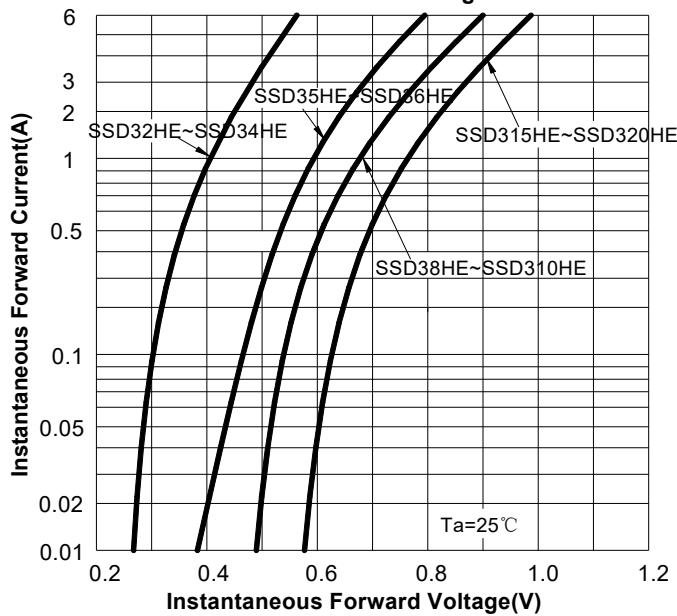


FIG4: Typical Reverse Characteristics

